Friday, October 5

Session C2-b — Advanced Techniques for Failure Analysis and Case Studies: Other Advanced Characterisation Techniques

Room: A

chairpersons

G. Breglio
University of Naples - Italy
M. Buzzo
Infineon Technologies - Austria

8:40

Invited paper

He-ion microscopy for device analysis

R. Van Gastel
University of Twente - The Netherlands

09:20 C2-b1-108

Nanoscale observations of resistive switching high and low conductivity states on TiN/HfO2/Pt structures

V. Iglesias[1], M. Lanza[1], M. Porti[1], M. Nafria[1], X. Aymerich[1], G. Bersuker[2], L. Liu[3], J. Kang[3], K. Zhang[4], Z. Shen[4]
[1]UAB (Universidad Autònoma de Barcelona) - Spain, [2]Sematech - United States, [3]Institute of Microelectronics, Peking University - China, [4]Peking University, Key Laboratory for the Physics and Chemistry of Nanodevices - China

09:40 C2-b2-131

Inverted high frequency scanning acoustic microscopy inspection of power semiconductor devices

M. Poschgan, J. Maynollo, M. Inselsbacher
Infineon Technologies - Austria

10:00 C2-b3-97

Spherical aberration correction in aplanatic solid immersion lens imaging using a MEMS deformable mirror

Y. Lu, E. Ramsay, C. Stockbridge, A. Yurt, H. Köklü, T. Bifano, S. Ünlü, B. Goldberg
Boston University - USA

10:20 C2-b4-29

Space domain reflectometry for opens detection location in micro bumps

J. Gaudestad[1], V. Talanov[1], P.C. Huang[2]
[1]Neocera - USA, [2]TSMC - Taiwan

Session E-c — Packaging, Assemblies, Passive Components and MEMS

Room: B

chairpersons

I. De Wolf
IMEC - Belgium
I. Iannacci
FBK-IRST - Italy

09:20 E-c1-10

Evaluation by three-point-bend and ball-on-ring tests of thinning process on silicon die strength

S. Barnat[1], H. Fremont[2], A. Guedon-Gracia[2], E. Cadalen[3]
[1]IMS-Bordeaux ; IPdia - France, [2]IMS-Bordeaux - France, [3]IPDiA - France